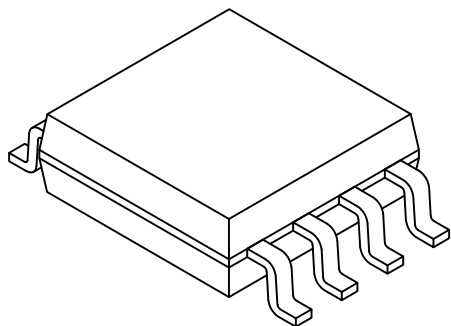
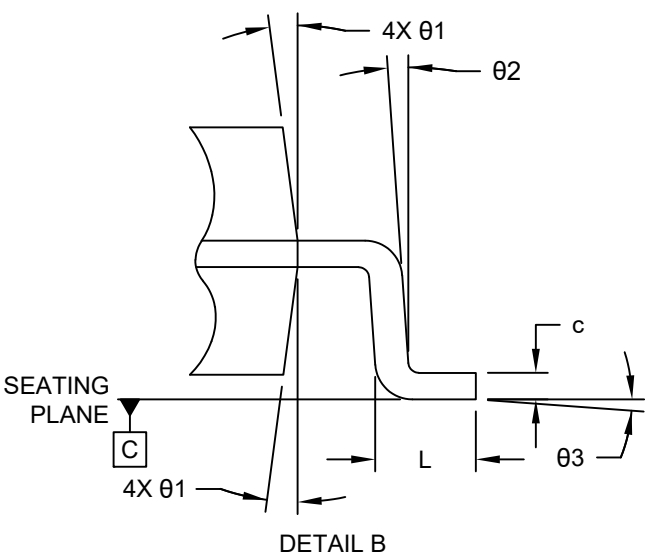


# 8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm (.208 Inch) Body [SOIJ]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	1.77	–	2.03
Standoff §	A1	0.05	–	0.25
Molded Package Thickness	A2	1.75	–	1.98
Overall Length	D	5.26 BSC		
Overall Width	E	7.94 BSC		
Molded Package Width	E1	5.25 BSC		
Terminal Width	b	0.36	–	0.51
Terminal Thickness	c	0.15	–	0.25
Terminal Length	L	0.51	–	0.76
Foot Angle	θ1	0°	–	8°
Lead Angle	θ2	0°	–	8°
Mold Draft Angle	θ3	–	–	15°

- Notes:
- Pin 1 visual index feature may vary, but must be located within the hatched area.
  - SOIJ – JEITA/EIAJ Standard, Formerly called SOIC
  - § – Significant Characteristic
  - Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
  - Dimensioning and tolerancing per ASME Y14.5M  
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
 REF: Reference Dimension, usually without tolerance, for information purposes only.